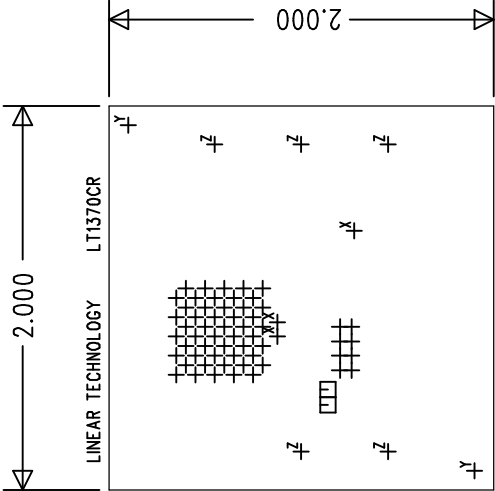
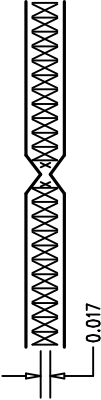


REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		8/3/97




**NOTES : Unless Otherwise Specified**

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD  
THICKNESS .062 +/- .006 TOTAL OF 2 LAYERS
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE  
ELECTRODEPOSITED TIN-LEAD COMPOSITION  
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC)
3. SOLDER MASK : BOTH SIDES USING GREEN PC-401 OR EQUIVALENT
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK
5. ALL DIMENSIONS ARE IN INCHES
6. SCORING:



SIZE	QTY	SYM	PLTD
20	58	+	PLTD
37	2	□	PLTD
25	3	X	PLTD
72	2	Y	NPLTD
95	5	Z	PLTD

## Fabrication Drawing

APPROVALS						1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900		
	INIT	DATE						
DRAWN								
CHECK								
DESIGN	KWL	8/3/97						
ENGR								
						</		